

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



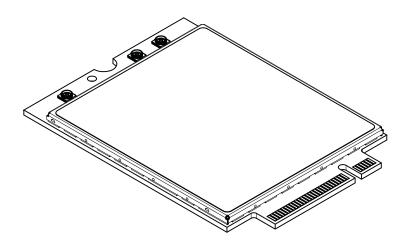






Product Technical Specification & Customer Design Guidelines

AirPrime EM7430





4116235 Rev 7 Proprietary and Confidential Contents subject to change

Important Notice

Due to the nature of wireless communications, transmission and reception of data can never be guaranteed. Data may be delayed, corrupted (i.e., have errors) or be totally lost. Although significant delays or losses of data are rare when wireless devices such as the Sierra Wireless modem are used in a normal manner with a well-constructed network, the Sierra Wireless modem should not be used in situations where failure to transmit or receive data could result in damage of any kind to the user or any other party, including but not limited to personal injury, death, or loss of property. Sierra Wireless accepts no responsibility for damages of any kind resulting from delays or errors in data transmitted or received using the Sierra Wireless modem, or for failure of the Sierra Wireless modem to transmit or receive such data.

Safety and Hazards

Do not operate the Sierra Wireless modem in areas where blasting is in progress, where explosive atmospheres may be present, near medical equipment, near life support equipment, or any equipment which may be susceptible to any form of radio interference. In such areas, the Sierra Wireless modem **MUST BE POWERED OFF**. The Sierra Wireless modem can transmit signals that could interfere with this equipment.

Do not operate the Sierra Wireless modem in any aircraft, whether the aircraft is on the ground or in flight. In aircraft, the Sierra Wireless modem **MUST BE POWERED OFF.** When operating, the Sierra Wireless modem can transmit signals that could interfere with various onboard systems.

Note: Some airlines may permit the use of cellular phones while the aircraft is on the ground and the door is open. Sierra Wireless modems may be used at this time.

The driver or operator of any vehicle should not operate the Sierra Wireless modem while in control of a vehicle. Doing so will detract from the driver or operator's control and operation of that vehicle. In some states and provinces, operating such communications devices while in control of a vehicle is an offence.

Limitation of Liability

The information in this manual is subject to change without notice and does not represent a commitment on the part of Sierra Wireless. SIERRA WIRELESS AND ITS AFFILIATES SPECIFICALLY DISCLAIM LIABILITY FOR ANY AND ALL DIRECT, INDIRECT, SPECIAL, GENERAL, INCIDENTAL, CONSEQUENTIAL, PUNITIVE OR EXEMPLARY DAMAGES INCLUDING, BUT NOT LIMITED TO, LOSS OF PROFITS OR REVENUE OR ANTICIPATED PROFITS OR REVENUE ARISING OUT OF THE USE OR INABILITY TO USE ANY SIERRA WIRELESS PRODUCT, EVEN IF SIERRA WIRELESS AND/OR ITS AFFILIATES HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES OR THEY ARE FORESEEABLE OR FOR CLAIMS BY ANY THIRD PARTY.

Notwithstanding the foregoing, in no event shall Sierra Wireless and/or its affiliates aggregate liability arising under or in connection with the Sierra Wireless product, regardless of the number of events, occurrences, or claims giving rise to liability, be in excess of the price paid by the purchaser for the Sierra Wireless product.

Patents This product may contain technology developed by or for Sierra Wireless Inc. This

product includes technology licensed from QUALCOMM®. This product is manufactured or sold by Sierra Wireless Inc. or its affiliates under one or more

patents licensed from InterDigital Group and MMP Portfolio Licensing.

Copyright ©2016 Sierra Wireless. All rights reserved.

Trademarks Sierra Wireless[®], AirPrime[®], AirLink[®], AirVantage[®] and the Sierra Wireless logo

are registered trademarks of Sierra Wireless, Inc.

Windows® and Windows Vista® are registered trademarks of Microsoft

Corporation.

QUALCOMM® is a registered trademark of QUALCOMM Incorporated. Used

under license.

Other trademarks are the property of their respective owners.

Contact Information

Sales information and technical support, including warranty and returns	Web: sierrawireless.com/company/contact-us/ Global toll-free number: 1-877-687-7795 6:00 am to 6:00 pm PST
Corporate and product information	Web: sierrawireless.com

Revision History

Revision number	Release date	Changes
1	October 2014	Initial release
2	February 2015	Updated Table 4-9 on page 49 (# of satellites) Corrected typo in Table 3-4 on page 32 (UIM_GND/UIM2_GND)

Revision number	Release date	Changes
3	March 2016	Updated Carrier Aggregation combinations (Table 1-2 on page 16) Added Windows 8.1 and Windows 10 references Updated RF block diagram (Figure 3-2 on page 25) Added notes indicating signals should not be driven until device is powered on, in Host Interface Pin Assignments on page 25 and Power On/Off Timing on page 55. Updated Antenna control section Added Envelope correlation coefficient to Table B-1 on page 73 Removed RFFE Power consumption values measured at 25C (changed from 30) Updated module weight (Table 7-1 on page 61) Added Packaging on page 95 Added signal strength for acquisition time values (Table 4-9 on page 49) Relabeled 'Max' column to 'Typ', specified voltage (Table 5-2 on page 66) Added max current value (Table 5-3 on page 52) Updated power-on/off timing values Updated temperature description/details to reflect device performance, including: Physical Features on page 16—Clarified temperature range as 'ambient'. Physical Features on page 16—Added ATIPCTEMP to note and adjusted suggested 'best performance' max temperature. Table 5-5 on page 54—Added explanatory note for TEMP_HI_WARN state. Table 7-1 on page 61—Clarified temperature range as 'ambient' Adjusted GNSS tracking sensitivity specification to -160 dBm from -161 dBm to reflect tolerance range of measurement (Table 4-9 on page 49). Added Figure 7-5, Copper Pad Location on Bottom Side of Module, on page 65. Updated USIM and USIM2 voltages in Table 3-1 on page 26. Added GPIO numbers to ANT_CTRL signal names in Table 3-1 on page 26. Modified note indicating USB2.0 and 3.0 support in USB Interface on page 31. Updated Rx Sensitivity and Tx Power Tolerance values, all RATs and Bands, in Conducted Rx Sensitivity ATx Power on page 48) and LTE CA Bandwidth Support on page 99. Added ITE bandwidth support (Table 4-2 on page 46) and LTE CA Bandwidth Support on page 99.
4	April 2016	Removed uplink CA columns from Table G-2, LTE CA Intra-band (Contiguous) Bandwidth Support, on page 100 and Table G-3, LTE CA Intra-band (Non-contiguous) Bandwidth Support, on page 101.
5	April 2016	Corrected indication of areas needing heat dissipation (bottom instead of top) in Thermal Considerations on page 64, and updated recommendation wording in general. Removed 'future' from Galileo support in Position Location (GNSS) on page 19
6	May 2016	Corrected ripple voltage value in Power Supply Noise on page 57 Corrected inrush current unit in Miscellaneous DC Power Consumption on page 52 Updated maximum current in Miscellaneous DC Power Consumption on page 52
7	August 2016	Removed gpsOneXTRA. Removed wireless coexistence topic; marked pins 60/62/64 as 'Reserved' (Table 3-1), updated system block (removed COEX signals) (Figure 3-1 on page 24). Added USB 3.0 signal to Signal Timing figure (Figure 5-2 on page 56); added USB 3.0 timing table (Table 5-8 on page 56). Updated USB 2.0 timing (Table 5-6 on page 56, Table 5-7 on page 56). Updated PCB thickness (Table 7-1 on page 61, Figure 7-2 on page 62).



Introduction
Supported RF bands
Physical Features
Application Interface Features
Modem Features
LTE Features
Short Message Service (SMS) Features
Position Location (GNSS)
Supporting Documents
Accessories
Required Connectors
Ordering Information
Integration Requirements
Standards Compliance
Electrical Specifications
Host Interface Pin Assignments
Power Supply
USB Interface
USB Throughput Performance
User-developed Drivers
SIM Interface
Control Interface (Signals)
WAKE_ON_WAN# — Wake Host
W_DISABLE1# (Wireless Disable) and W_DISABLE2# (GNSS Disable). 36
Full_Card_Power_Off# and RESET#
WWAN_LED#—LED Output

Antenna Control	39
RF Specifications	41
RF Connections4	41
Shielding	
Antenna and Cabling	
Ground Connection	43
Interference and Sensitivity	43
Interference from Other Wireless Devices	43
Host-generated RF Interference	44
Device-generated RF Interference	44
Methods to Mitigate Decreased Rx Performance	
Radiated Spurious Emissions (RSE)	45
Radiated Sensitivity Measurement	45
Sierra Wireless' Sensitivity Testing and Desensitization Investigation 4	
Sensitivity vs. Frequency	45
Supported Frequencies	46
Conducted Rx Sensitivity / Tx Power	48
GNSS Specifications	49
Davis	
Power	
Power Consumption	
Module Power States	
Power State Transitions	54
Power Interface	
Power Ramp-up	
Timing	
Power Supply Noise	
SED (Smart Error Detection)	
Tx Power Control	57
Software Interface	59
Software Interface	

USB Interface	59
Mechanical and Environmental Specifications	61
Device Views	62
Labeling	63
Electrostatic Discharge (ESD)	63
Thermal Considerations	64
Module Integration Testing	65
Regulatory Compliance and Industry Certifications	67
Important Notice	67
Safety and Hazards	67
Audio Support	
PCM/I2S Audio Interface	70
Antenna Specification	73
Recommended Main/Diversity Antenna Specifications	73
Recommended GNSS Antenna Specifications	75
Antenna Tests	76
Design Checklist	77
Testing	79
AT Command Entry Timing Requirement	79
Acceptance Testing	79
Acceptance Test Requirements	
Acceptance Test Procedure	
Certification Testing	80
Production Testing	81

Functional Production Test	. 81
Production Test Procedure	82
UMTS (WCDMA) RF Transmission Path Test	85
UMTS (WCDMA) RF Receive Path Test	86
LTE RF Receive Path Test	88
GNSS RF Receive Path Test	90
Quality Assurance Testing	. 90
Suggested Testing Equipment	. 91
Testing Assistance Provided by Sierra Wireless	. 91
IOT/Operator Testing	. 91
Extended AT Commands for Testing	. 92
Packaging	95
References	97
References Sierra Wireless Documents	
	. 97
Sierra Wireless Documents	. 97
Sierra Wireless Documents	. 97 97
Sierra Wireless Documents	. 97 97 97
Sierra Wireless Documents Command Documents Other Sierra Documents Industry/Other Documents LTE CA Bandwidth Support	97 97 97 97
Sierra Wireless Documents Command Documents Other Sierra Documents Industry/Other Documents	97 97 97 97



Table 1-1: Supported RF Bands	15
Table 1-2: Carrier Aggregation Combinations	16
Table 1-3: Required Host-Module Connectors	20
Table 2-1: Standards Compliance	21
Table 3-1: Host Interface (67-pin) Connections—Module View	26
Table 3-2: Power and Ground Specifications	31
Table 3-3: USB Interfaces	31
Table 3-4: SIM Interface Signals	32
Table 3-5: Module Control Signals	35
Table 3-6: W_DISABLE_N Usage	37
Table 3-7: Full_Card_Power_Off# and RESET# Usage	38
Table 3-8: Antenna Control Signals	39
Table 4-1: LTE Frequency Bands	46
Table 4-2: LTE Bandwidth Support	46
Table 4-3: WCDMA Frequency Bands Support	47
Table 4-4: TD-SCDMA Frequency Bands	47
Table 4-5: Conducted Rx (Receive) Sensitivity—LTE Bands	48
Table 4-6: Conducted Rx (Receive) Sensitivity—UMTS Bands	48
Table 4-7: Conducted Rx (Receive) Sensitivity—TD-SCDMA Bands	49
Table 4-8: Conducted Tx (Transmit) Power Tolerances	49
Table 4-9: GNSS Specifications	49
Table 5-1: Averaged Standby DC Power Consumption	51
Table 5-2: Averaged Call Mode DC Power Consumption	52
Table 5-3: Miscellaneous DC Power Consumption	52
Table 5-4: Module Power States	53
Table 5-5: Power State Transition Trigger Levels	54
Table 5-6: USB 2.0 Power-On/Off Timing Parameters (Double Enumeration).	56
Table 5-7: USB 2.0 Power-On/Off Timing Parameters (Single Enumeration) .	56

Table 5-8: USB 3.0 Power-On/Off Timing Parameters (Single Enumeration) .	56
Table 5-9: Dynamic Power Control of SAR Backoff State	58
Table 7-1: Mechanical and Environmental Specifications	61
Table A-1: Host interface (67-pin) Connections—Module View	69
Table A-2: PCM/I2S Interface Signals	70
Table A-3: PCM Timing	71
Table A-4: Master Transmitter with Data Rate = 3.072 MHz (±10%)	72
Table B-1: Antenna Requirements	73
Table B-2: GNSS Antenna Requirements	75
Table C-1: Hardware Integration Design Considerations	77
Table 4-1: Test Settings—UMTS Transmission Path	85
Table 4-2: Test Settings—UMTS Receive Path	86
Table 4-3: Test Settings—LTE Receive Path	88
Table 4-4: Extended AT Commands	92
Table G-1: LTE CA Inter-band Bandwidth Support	99
Table G-2: LTE CA Intra-band (Contiguous) Bandwidth Support	100
Table G-3: LTE CA Intra-band (Non-contiguous) Bandwidth Support 1	101
Table H-1: Acronyms and Definitions	103



Figure 3-1: System Block Diagram	24
Figure 3-2: Expanded RF Block Diagram	25
Figure 3-3: SIM Application Interface (applies to both SIM interfaces)	33
Figure 3-4: SIM Card Contacts (Contact View)	34
Figure 3-5: Recommended WAKE_ON_WAN# Connection	36
Figure 3-6: Recommended Wireless Disable Connection	37
Figure 3-7: Example LED	39
Figure 4-1: Module Connectors	41
Figure 5-1: Voltage/Temperature Monitoring State Machines	55
Figure 5-2: Signal Timing (Full_Card_Power_Off#, and USB Enumeration)	56
Figure 7-1: Top View	62
Figure 7-2: Dimensioned View	62
Figure 7-3: Unit Label	63
Figure 7-4: Shield Locations (Top View)	64
Figure 7-5: Copper Pad Location on Bottom Side of Module	65
Figure A-1: PCM_SYNC Timing	70
Figure A-2: PCM Codec to Module Timing	71
Figure A-3: Module to PCM Codec Timing	71
Figure A-4: I2S Transmitter Timing Diagram	72
Figure 5-1: Device Placement in Module Tray	95
Figure 5-2: Shipping Package	96

>> 1: Introduction

The Sierra Wireless EM7430 Embedded Module is an M.2 module that provides LTE, UMTS, TD-SCDMA, and GNSS connectivity for notebook, ultrabook, tablet computers, and M2M applications over several radio frequency bands.

Supported RF bands

The modem, based on Qualcomm's MDM9230 baseband processor, supports data operation on LTE and UMTS networks over the bands described in Table 1-1, with LTE carrier aggregation (CA) as described in Table 1-2.

Table 1-1: Supported RF Bands

							-	Band	c							
Technology								anu	<u> </u>							Data Rates/Notes
	1	3	5	6	7	8	9	18	19	21	28	38	39	40	41	
LTE	F	F	F		F	F		F	F	F	F	Т	Т	Т	Т	Data rates: Downlink (Cat 6): FDD: 300 Mbps TDD: 222 Mbps Uplink (Cat 6): FDD: 50 Mbps TDD: 26 Mbps Notes: Downlink MIMO support (2x2; 4x2) F=FDD; T= TDD
DC-HSPA+ HSPA+ HSPA UMTS	Y		Y	Y		Y	Y		Y				N/A			Data rates: Downlink (Cat 24): Up to 42 Mbps Uplink (Cat 6): Up to 5.76 Mbps Notes: Diversity support

Table 1-1: Supported RF Bands

Technology		Bands										Data Rates/Notes				
recimology	1	3	5	6	7	8	9	18	19	21	28	38	39	40	41	Data nates/Notes
TD-SCDMA													Y			Data rates: Downlink: Up to 2.8 Mbps Uplink: Up to 2.2 Mbps Spreading rate: Downlink: 1.28 Mcps Notes: Diversity support
GNSS	•	GLC BeiD	6: 157 NAS Oou: 1 eo ¹ :	S: 16	02 M 098 N	lHz ∕lHz										

^{1.} Future firmware upgrade

Table 1-2: Carrier Aggregation Combinations

1 + 8/18/19/21
3 + 5/7/19/28
5 + 3/7
7 + 3/5/7/28
8 + 1
18 + 1
19 + 1/3/21
21 + 1/19
28 + 3/7
38 + 38
39 + 39
40 + 40
41 + 41

Physical Features

M.2 form factor—WWAN Type 3042-S3-B (in WWAN—USB 3.0 Port Configuration 2), as specified in [8] PCI Express NGFF (M.2) Electrome-

chanical Specification Revision 1.0. (Note: Any variations from the specification are detailed in this document.)

- Ambient operating temperature range:
 - Class A (3GPP compliant): -30°C to +70°C
 - Class B (operational, non-3GPP compliant): -40°C to +85°C (reduced operating parameters required)

Important: The internal module temperature (reported by AT!PCTEMP) must be kept below 90°C. For best performance, the internal module temperature should be kept below 80°C. Proper mounting, heat sinks, and active cooling may be required, depending on the integrated application.

Application Interface Features

- USB interface (QMI) for Windows 7, Linux, and Android
- MBIM for Windows 8.1 and Windows 10
- AT command interface ([1] AT Command Set for User Equipment (UE) (Release 6) (Doc# 3GPP TS 27.007), plus proprietary extended AT commands) in [2] AirPrime EM74xx/MC74xx AT Command Reference (Doc# 4117727)
- Software Development Kits (SDK),including API (Application Program Interface) functions:
 - Windows 7, Windows 8.1, Windows 10
 - Linux
- Support for active antenna control via dedicated antenna control signals (ANTCTL0:3)
- Dynamic power reduction support via software and dedicated GPIO (DPR)
- OMA DM (Open Mobile Alliance Device Management)
- FOTA (Firmware Over The Air)

Note: OMA DM and FOTA support is operator-dependent.

Modem Features

- LTE / DC-HSPA+ / HSPA+ / HSPA / UMTS (WCDMA) operation
- Multiple (up to 16) cellular packet data profiles
- Traditional modem COM port support for AT commands
- USB suspend / resume
- Sleep mode for minimum idle power draw
- SIM application tool kit with proactive SIM commands
- Enhanced Operator Name String (EONS)
- Mobile-originated PDP context activation / deactivation
- Support QoS profile
 - · Release 99 QoS negotiation—Background, Interactive, and Streaming
 - Release 97—Precedence Class, Reliability Class, Delay Class, Peak Throughput, Mean Throughput

- Static and Dynamic IP address. The network may assign a fixed IP address or dynamically assign one using DHCP (Dynamic Host Configuration Protocol).
- PAP and CHAP support
- PDP context type (IPv4, IPv6, or IPv4v6). IP Packet Data Protocol context supports dual IPv4v6.
- RFC1144 TCP/IP header compression

LTE Features

- Carrier aggregation:
 - · DL LTE-FDD
 - · 20 MHz intraband non-contiguous
 - 40 MHz interband
 - · DL LTE-TDD
 - · 40 MHz intraband contiguous and non-contiguous
 - 40 MHz interband
- CSG support (LTE Femto)
- LTE Advanced receivers (NLIC, elCIC, felCIC)
- Basic cell selection and system acquisition
 - · PSS/SSS/MIB decode
 - SIB1–SIB16 decoding
- NAS/AS security procedures
 - Snow 3G/AES/ZUC security
- CQI/RI/PMI reporting
- Paging procedures
 - · Paging in Idle and Connected mode
- Dedicated bearer
 - Network-initiated dedicated bearer
 - UE-initiated dedicated bearer
- Multiple PDN connections (IPv4 and IPv6 combinations), subject to operating system support.
- Connected mode intra-LTE mobility
- Idle mode intra-LTE mobility
- iRAT between LTE/3G for idle and connection release with redirection
- Detach procedure
 - · Network-initiated detach with reattach required
 - · Network-initiated detach followed by connection release

Short Message Service (SMS) Features

- Mobile-originated and mobile-terminated SMS over IMS for LTE
- Mobile-originated and mobile-terminated SMS over SGs for LTE

Position Location (GNSS)

- Customizable tracking session
- Automatic tracking session on startup
- Concurrent standalone GPS, GLONASS, Galileo, and BeiDou
- Assisted GPS (A-GPS) SUPL1.0
- Assisted GPS/GLONASS SUPL2.0
- GPS/GLONASS on dedicated connector or diversity connector
- BeiDou on dedicated connector, or on diversity connector with reduced performance
- Galileo on dedicated connector or diversity connector (future firmware upgrade)

Supporting Documents

Several additional documents describe module design, usage, integration, and other features. See References on page 97.

Accessories

A hardware development kit is available for AirPrime M.2 modules. The kit contains hardware components for evaluating and developing with the module, including:

- Development board
- Cables
- Antennas
- Other accessories

For over-the-air LTE testing, ensure that suitable antennas are used.

Required Connectors

Table 1-3 describes the connectors used to integrate the EM7430 Embedded Module into your host device.

Table 1-3: Required Host-Module Connectors¹

Connector type	Description
RF cables	Mate with M.2-spec connectors
	Three connector jacks (I-PEX 20448-001R-081 or equivalent)
EDGE (67 pin)	Slot B compatible—Per the M.2 standard ([8] PCI Express NGFF (M.2) Electromechanical Specification Revision 1.0), a generic 75 pin position EDGE connector on the motherboard uses a mechanical key to mate with the 67 pin notched module connector.
	 Manufacturers include LOTES (part #APCI0018-P001A01), Kyocera, JAE, Tyco, and Longwell.
SIM	Industry-standard connector. See SIM Interface on page 32 for details.

^{1.} Manufacturers/part numbers are for reference only and are subject to change. Choose connectors that are appropriate for your own design.

Ordering Information

To order, contact the Sierra Wireless Sales Desk at +1 (604) 232-1488 between 8 AM and 5 PM Pacific Time.

Integration Requirements

Sierra Wireless provides, in the documentation suite, guidelines for successful module integration and offers integration support services as necessary.

When integrating the EM7430 Embedded Module, the following items must be addressed:

- Mounting—Effect on temperature, shock, and vibration performance
- Power supply—Impact on battery drain and possible RF interference
- Antenna location and type—Impact on RF performance
- Regulatory approvals—As discussed in Regulatory Compliance and Industry Certifications on page 67.
- Service provisioning—Manufacturing process
- Software—As discussed in Software Interface on page 59.
- Host interface—Compliance with interface voltage levels

>> 2: Standards Compliance

The EM7430 Embedded Module complies with the mandatory requirements described in the following standards. The exact set of requirements supported is network operator-dependent.

Table 2-1: Standards Compliance

Technology	Standards						
LTE	3GPP Release 11						
UMTS	3GPP Release 9						

>> 3: Electrical Specifications

The system block diagram in Figure 3-1 represents the EM7430 module integrated into a host system. The module includes the following interfaces to the host:

- Full_Card_Power_Off#—Input supplied to the module by the host—active-low to turn the unit off, or active-high to turn the unit on
- W_DISABLE1#—Active low input from the host to the EM7430 disables the main RF radio.
- W_DISABLE2#—Active low input from the host to the EM7430 disables the GNSS radio receiver.
- WAKE_ON_WAN#—Active low output used to wake the host when specific events occur.
- WWAN_LED#—Active-low LED drive signal provides an indication of RADIO ON state, either WWAN or GNSS.
- RESET#—Active low input from the host used to reset the module.
- Antenna—Three RF connectors (main (Rx/Tx), GNSS, and auxiliary (diversity/MIMO/GNSS)). For details, see RF Specifications on page 41.
- Antenna control—Four signals that can be used to control external antenna switches—two for high band, and two for low band.
- Dynamic power control—Signal used to adjust Tx power to meet FCC SAR requirements. For details, see Tx Power Control on page 57.).
- Dual SIM—Supported through the interface connector. The SIM cavities / connectors must be placed on the host device for this feature.
- SIM detect—Internal pullup on the module detects whether a SIM is present or not:
 - If a SIM is not inserted, the pin must be shorted to ground.
 - · If a SIM is present, the pin will be an open circuit.
- USB—USB 2.0 and USB 3.0 interfaces to the host for data, control, and status information.

The EM7430 has two main interface areas—the host I/O connector and the RF ports. Details of these interfaces are described in the sections that follow.

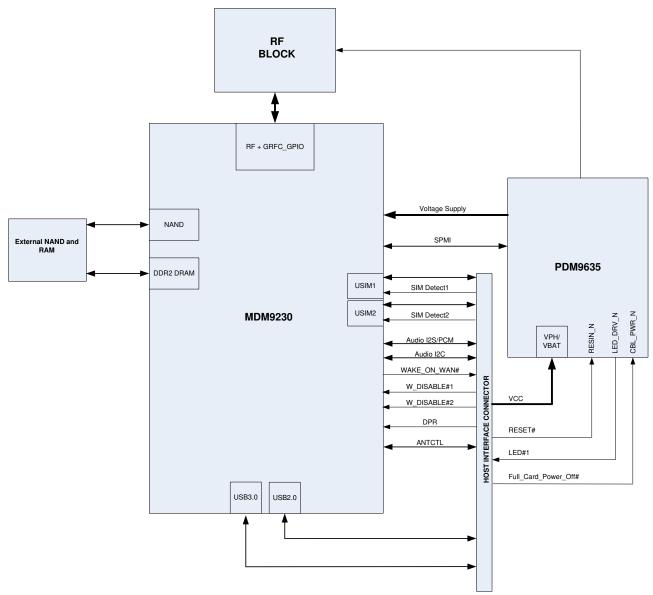


Figure 3-1: System Block Diagram

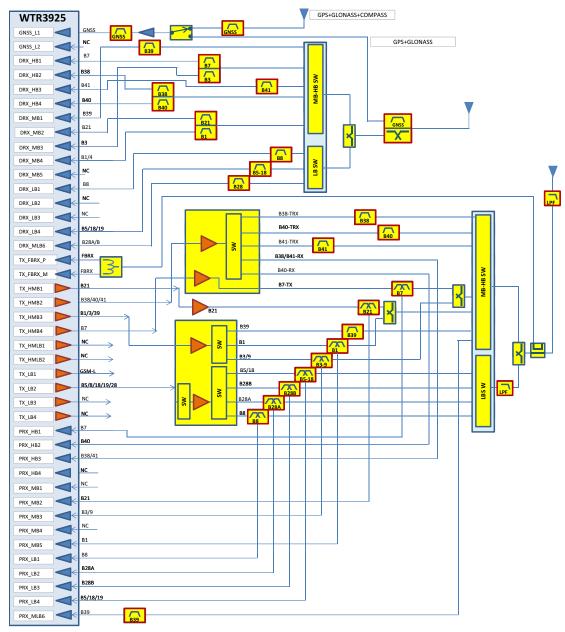


Figure 3-2: Expanded RF Block Diagram

Host Interface Pin Assignments

The EM7430 host I/O connector provides pins for power, serial communications, and control. Pin assignments are listed in Table 3-1.

Refer to the following tables for pin details based on interface types:

- Table 3-2, Power and Ground Specifications, on page 31
- Table 3-3, USB Interfaces, on page 31
- Table 3-4, SIM Interface Signals, on page 32